# Application Development Packs



Elma's AppliPak (Application Development Pack) is a fully integrated embedded computing solution combining a single board computer based on open architectures (VME, VPX, cPCI, etc.) with your choice of state of the art storage and/or I/O mezzanine cards, operating systems support and device drivers.

Staying on schedule is more important now than ever. For over 20 years, Elma's AppliPaks have addressed critical board level integration issues where a tech refresh or an entirely new board set for a custom or existing platform is needed.



AppliPaks range in complexity from off-the-shelf systems with simple operating system and device driver load to fully ruggedized assemblies with custom OS and driver integration.

#### Features:

- A Single Board Computer from our wide range of Intel and Freescale CPU options
- Choice of mezzanine based I/O and storage options including serial, audio, video, Ethernet, FPGA I/O, solid state or rotating drives and more
- VxWorks, Linux or Windows OS, and drivers with kernel configuration, optional tools and boot file
- Rear transition module (RTM) or breakout board
- Extended temperature ranges, as well as conformal coating when required
- Assembly level testing, support and life cycle management

#### **Benefits:**

- Lower support and procurement costs each assembly is sold and supported under one model number with Elma as your single point of contact
- Concentrate your efforts on your core business
- Cost containment and risk mitigation take the guess work out of system design time and costs and rely on Elma for all integration work and scheduling
- Fully tested and installation ready before shipment



# AppliPaks Application Development Packs



### **Example AppliPaks**

AppliPaks and Rugged AppliPaks are developed using products from our wide range of partners in the embedded computing industry as well as products from our own extensive line of storage and I/O solutions.

Our long term partnership with industry leaders like Emerson, Concurrent, GE, Interface Concept, and Tech Source results in bundled solutions using best in class products to meet most every application need.



## **Enhanced Serial Communications System**

AppliPak consisting of an Emerson MVME6100, SBC, 8 additional mezzanine based 8 RS422 asynchronous serial ports and 2 additional Ethernet ports via mezzanine

#### **Legacy I/O Support**

AppliPak consisting of an MVME5110 SBC and a configurable FPGA module supporting VSB bus



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### **Example AppliPaks**

# High Capacity Front Removable Storage System

AppliPak consisting of a quad Core i7 SBC plus dual front-removable drives using Elma 9271 ShuttleStor mezzanine cards











#### **Weapons Control System**

Rugged and conformal coated
AppliPak consisting of a Core 2 Duo
SBC, additional mezzanine based
storage and Ethernet port capacity
plus mating 6U carrier for future I/O
expansion as needed

S = SCSI

Z = Custom

X = No I/O Mezzanine

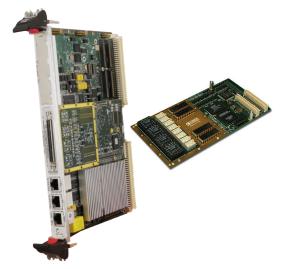
# AppliPaks



## **Example AppliPaks**

### **In Flight Avionics System**

AppliPak consisting of an MVME6100 SBC and a 1553 mezzanine card



Order Information — A	
Use the chart below to create a basic AppliPak co	infiguration, then talk to your sales representative for complete details.
Bus Architecture  C = CPCI (PICMG)  V = VITA	Mezzanine Expansion Card  N = No Y = Yes
SBC  I = Intel O = Other P = PowerPC	RTM  N = No Y = Yes
Board Size  3 = 3U 6 = 6U	Operating Systems  L = Linux O = Other S = Solaris
Storage Mezzanine  F = Fixed  M = Multiple/Combination  O = Other	V = VxWorks W = Windows X = No OS
<ul> <li>R = Removable</li> <li>S = Secure</li> <li>X = No storage mezzanine</li> <li>Z = Custom</li> </ul>	Conformal Coating Y/N
I/O Mezzanine  E = Ethernet	Temperature Requirements  O = Other S = +5C to +40C
M = Multiple / Combination O = Other R = Serial	Application Software

N = No

Y = Yes